Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTIONS:**

1. **N. 1A**
2. **1B**
3. **N. 1R**
4. **N. 1Q**
5. **2Q**
6. **2CX**
7. **2CXRX**
8. **GND**
9. **N. 2A**
10. **2B**
11. **N. 2R**
12. **N. 2Q**
13. **1Q**
14. **1CX**
15. **1CXRX**
16. **VCC**

**.081”**

**.071”**

**2 1 16 15**

**14**

**13**

**12**

**11**

**7 8 8 9 10**

**3**

**4**

**5**

**6**

**HC**

**221T**

**MASK**

**ID**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .004” X .004”**

**Backside Potential: VCC or leave FLOATING**

**Mask Ref: HC221T**

**APPROVED BY: DK DIE SIZE .071” X .081” DATE: 8/25/16**

**MFG: TEXAS INSTRUMENTS THICKNESS .024” P/N: 54HC221**

**DG 10.1.2**

#### Rev B, 7/19/02